

**AMENDMENTS TO THE ABSTRACT:**

Please amend the Abstract of the Disclosure as follows:

~~The invention relates to a~~ A process for joining substrates having electrical, semiconducting, mechanical and/or optical components, and to a composite element is provided. The process is to be suitable for ~~the~~ substrates ~~which~~ that are to be joined substantially irrespective of material and ~~in particular also~~ for sensitive substrates, ~~is to have a high chemical and physical stability and/or is to produce a hermetic cavity~~. According to the ~~invention~~ process, a raised frame, in particular formed from anodically bondable glass, is applied by evaporation coating to one of the two substrates in order to serve as a joining element.